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**Jung et al.**

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(54) **SEMICONDUCTOR DEVICE INCLUDING CAPACITOR WITH PILLAR-SHAPED BOTTOM ELECTRODE**

(58) **Field of Classification Search**  
CPC .... H10B 12/03; H10B 12/033; H10B 12/315; H01L 28/40; H01L 28/90

See application file for complete search history.

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(65) **Prior Publication Data**

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(57) **ABSTRACT**

**Related U.S. Application Data**

(63) Continuation of application No. 17/571,935, filed on Jan. 10, 2022, now Pat. No. 11,716,840.

A semiconductor device including a substrate; bottom electrodes on the substrate, each bottom electrode including a first region and a second region, the second region containing an additional element relative to the first region; a first supporting pattern on the substrate and in contact with a portion of a side surface of each bottom electrode; a top electrode on the bottom electrodes; a dielectric layer between the bottom electrodes and the top electrode; and a capping layer between the bottom electrodes and the dielectric layer, the capping layer covering a top surface and a bottom surface of the first supporting pattern, wherein the second region is in contact with the capping layer, and the capping layer and the dielectric layer include different materials from each other.

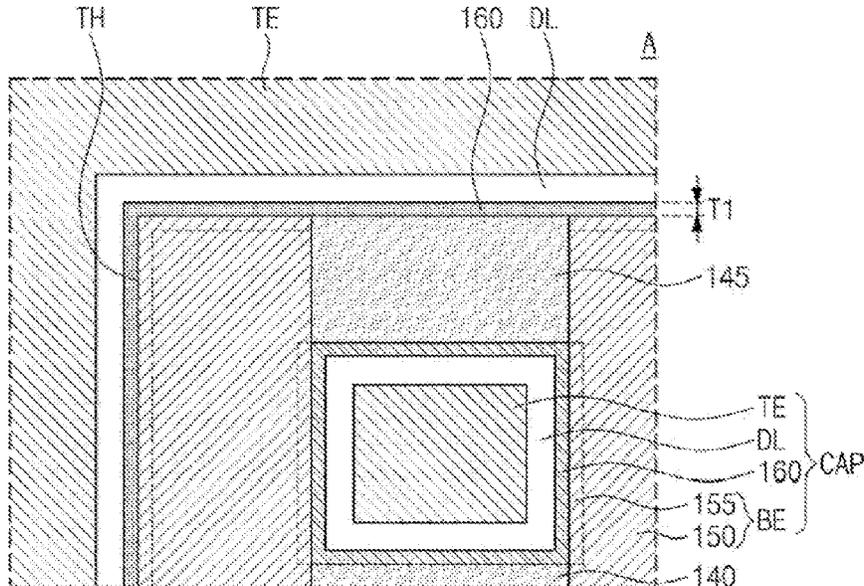
**Foreign Application Priority Data**

Jul. 5, 2021 (KR) ..... 10-2021-0088022

**20 Claims, 12 Drawing Sheets**

(51) **Int. Cl.**  
**H10B 12/00** (2023.01)

(52) **U.S. Cl.**  
CPC ..... **H10B 12/315** (2023.02); **H10B 12/033** (2023.02)



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FIG. 1

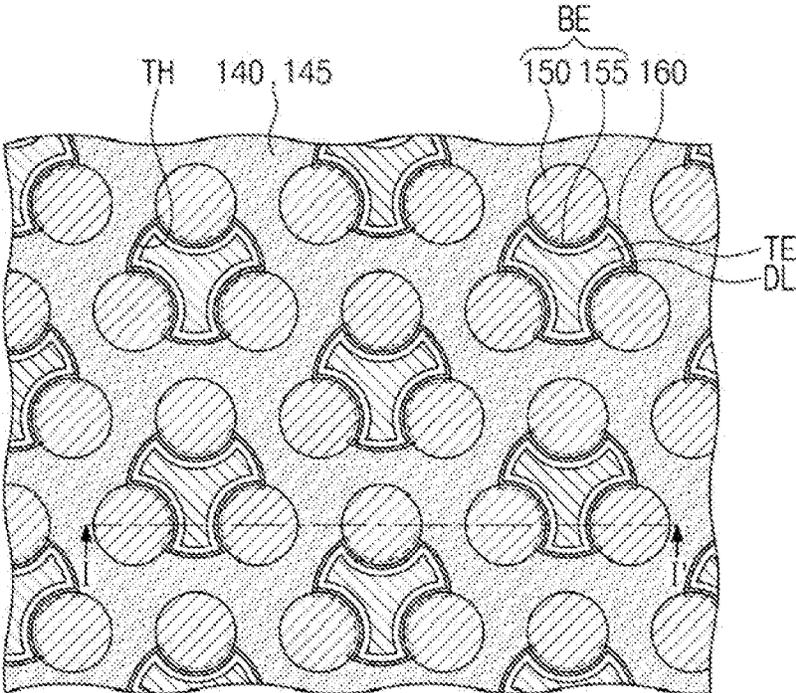




FIG. 4

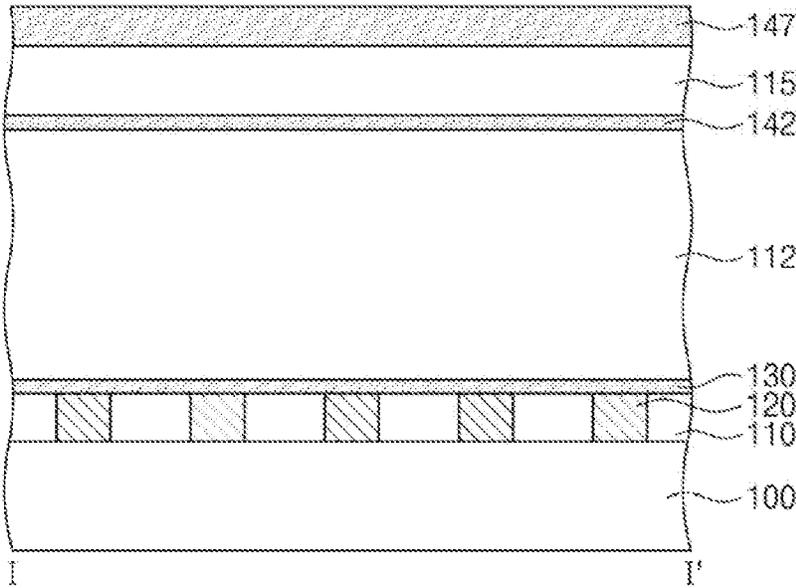


FIG. 5

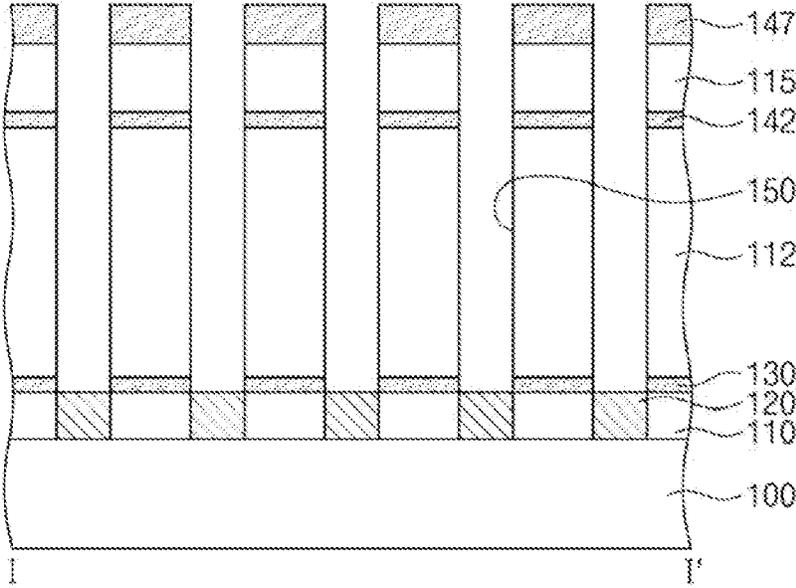


FIG. 6

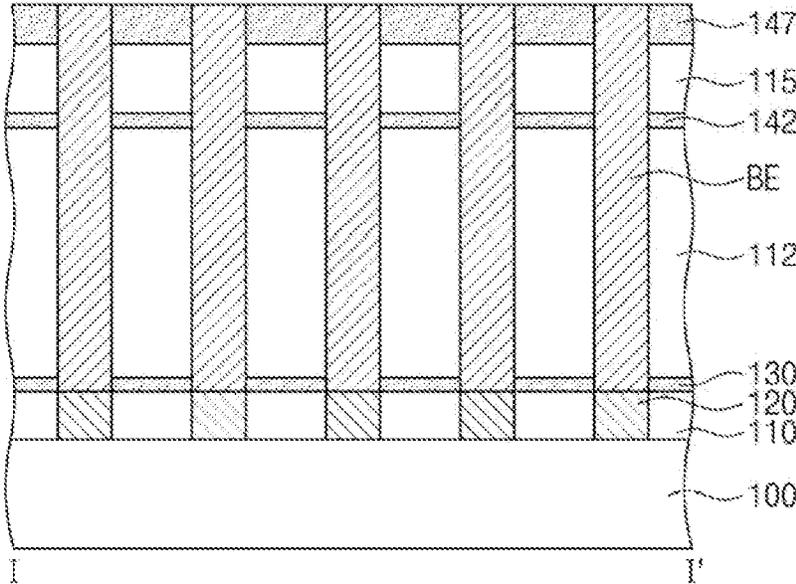


FIG. 7

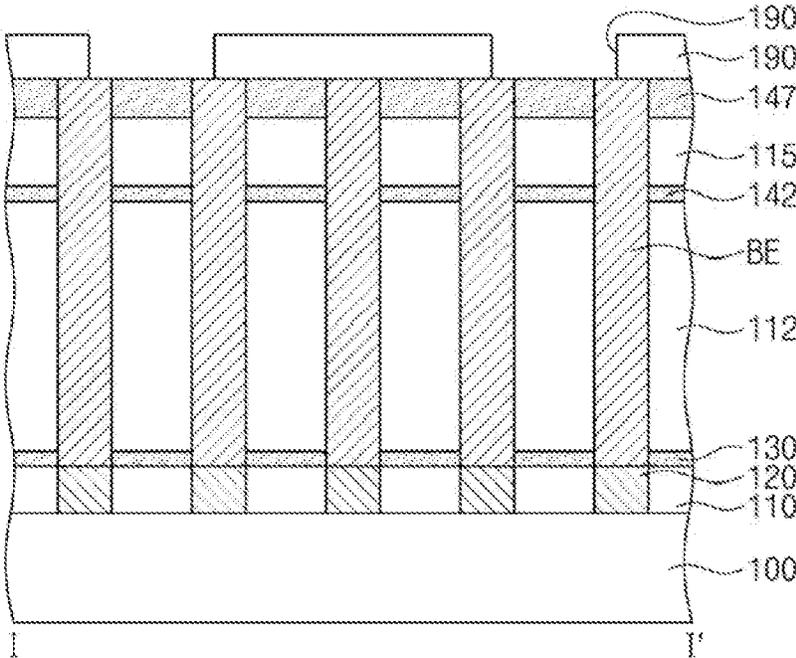


FIG. 8

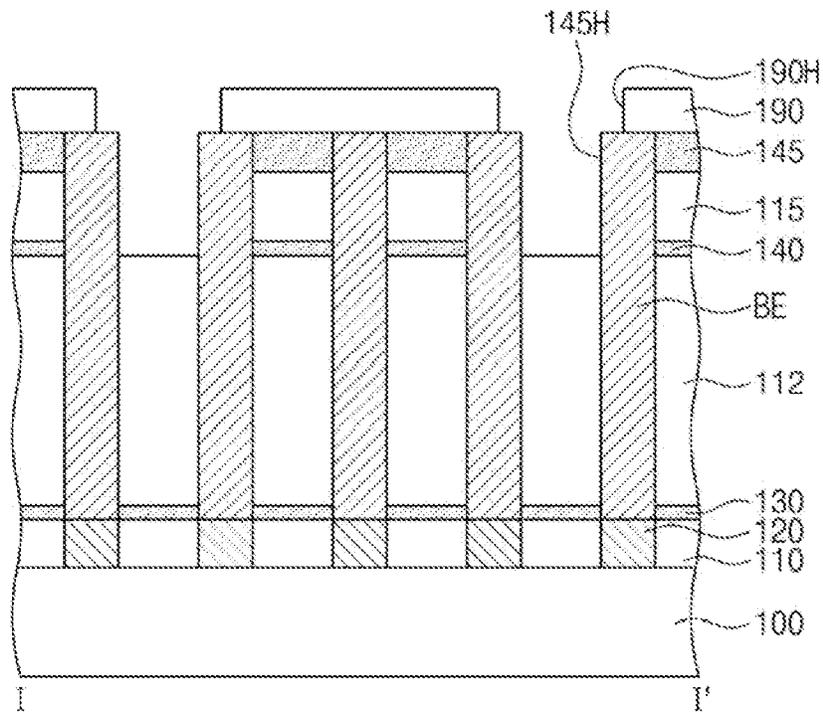


FIG. 9

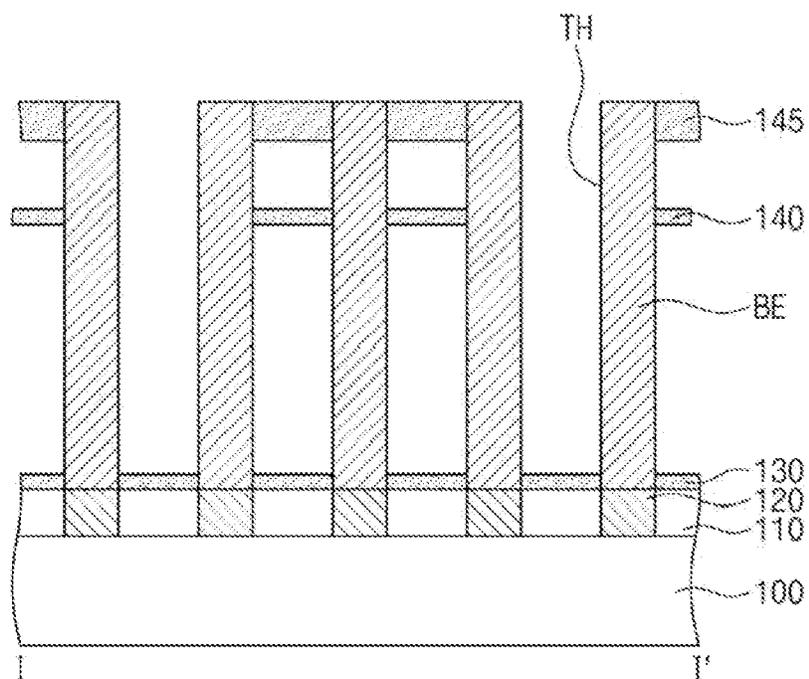


FIG. 10

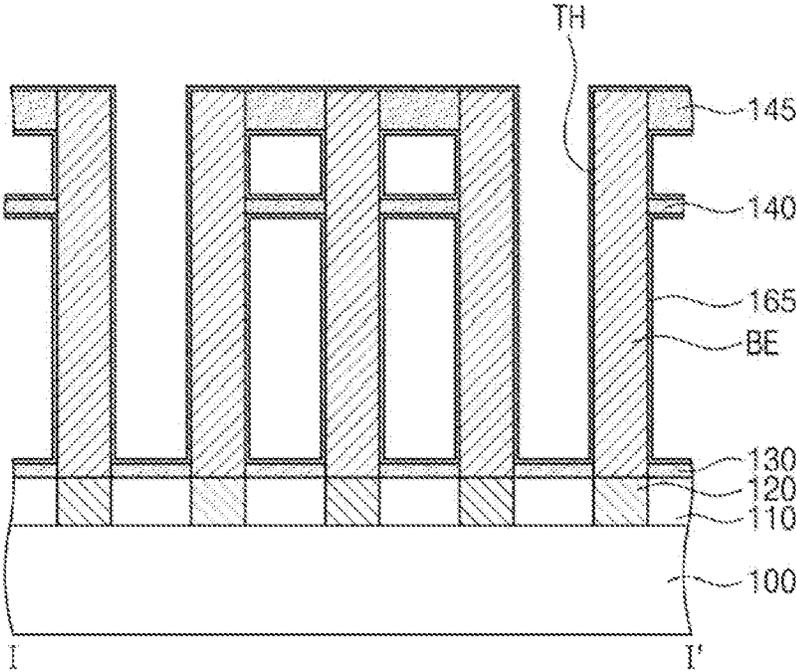


FIG. 11

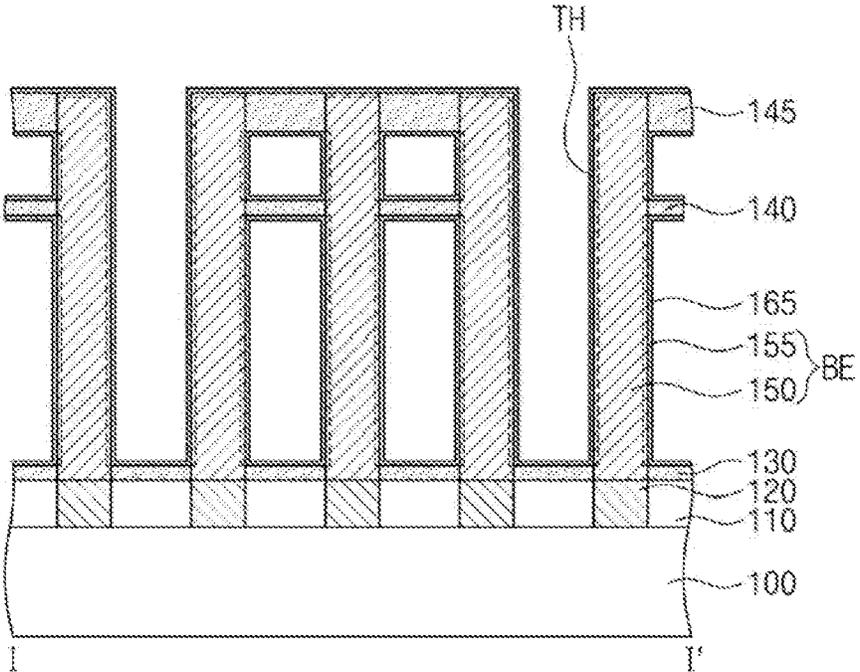


FIG. 12

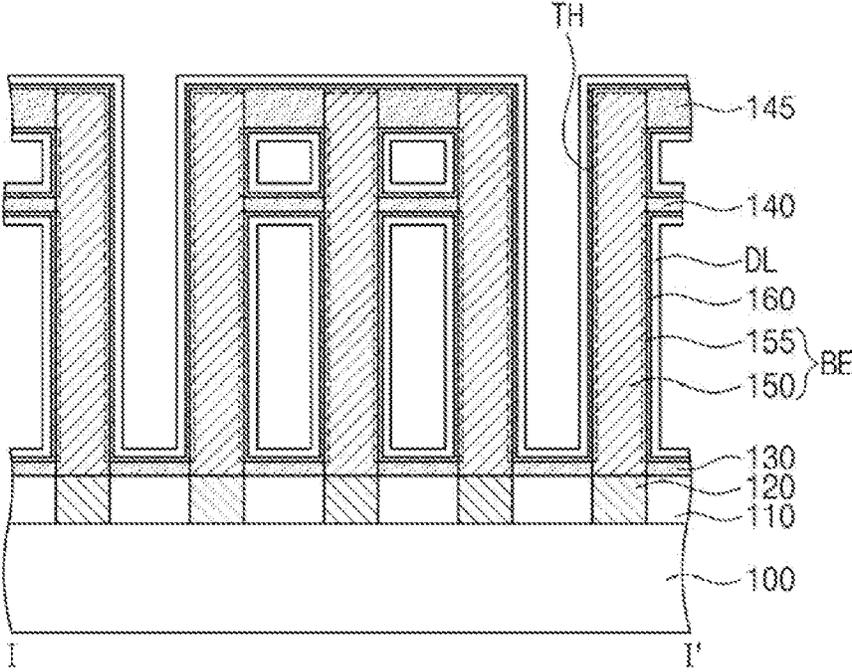


FIG. 13

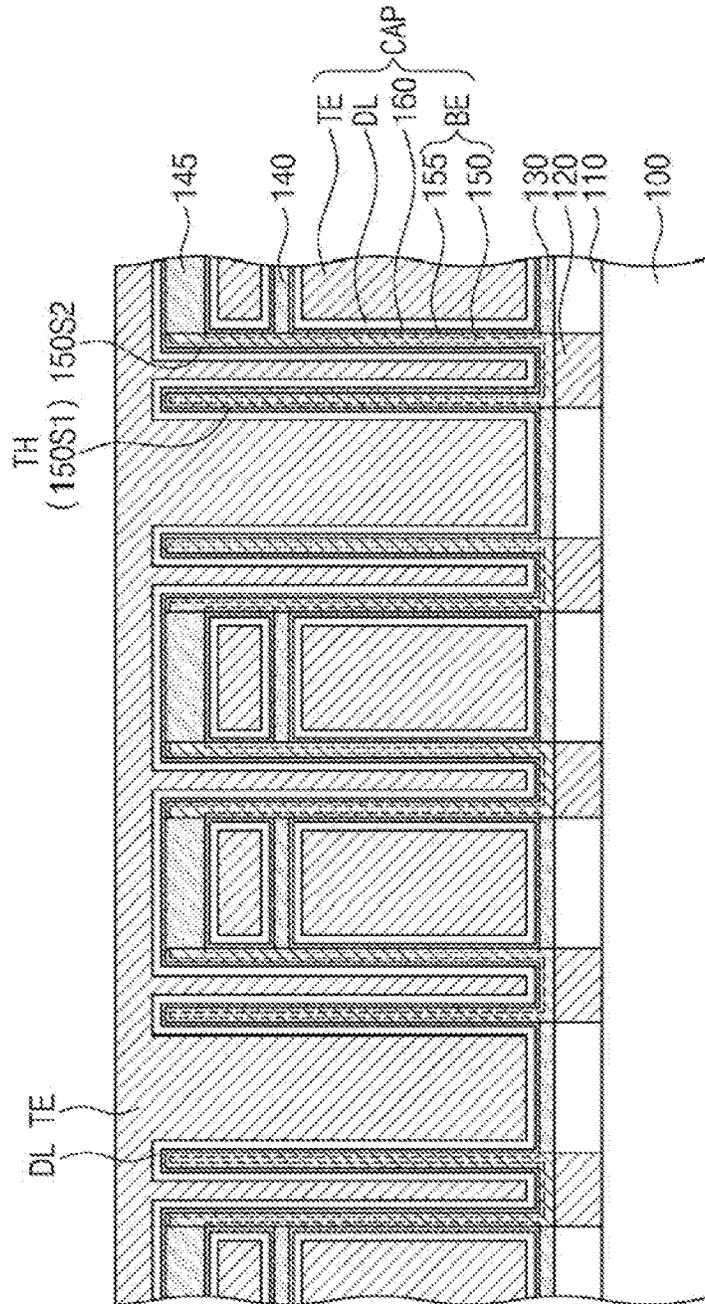


FIG. 14

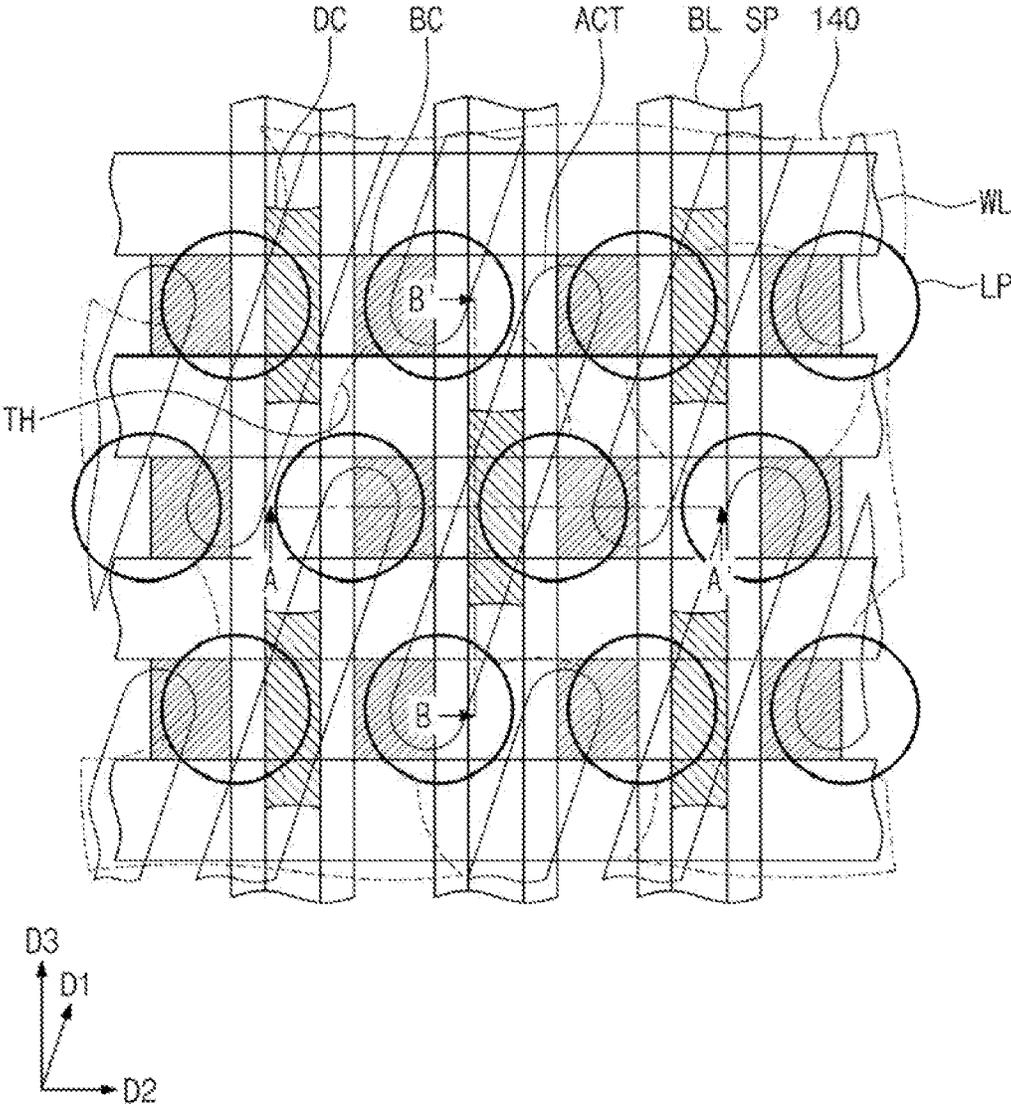




FIG. 16

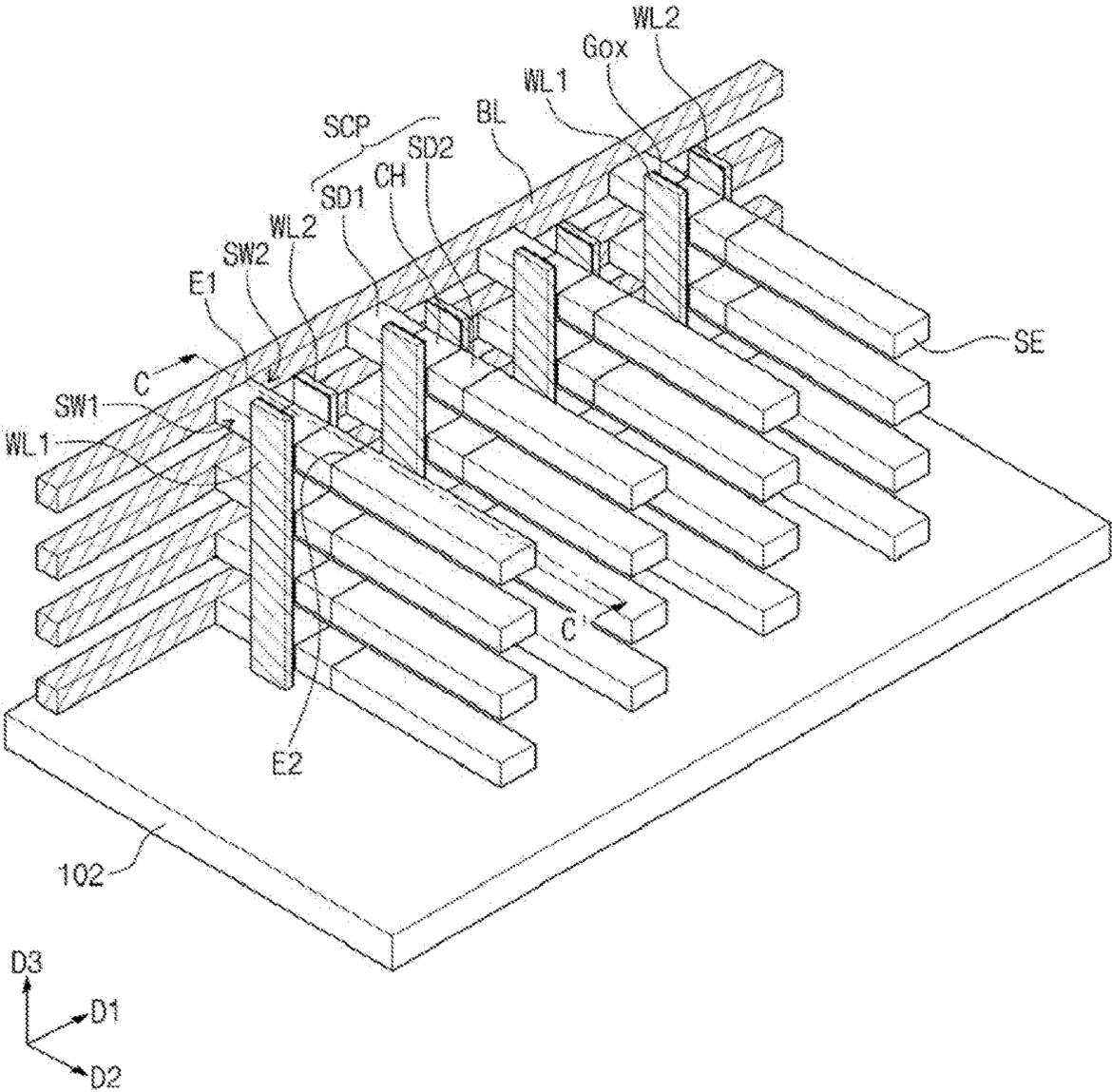
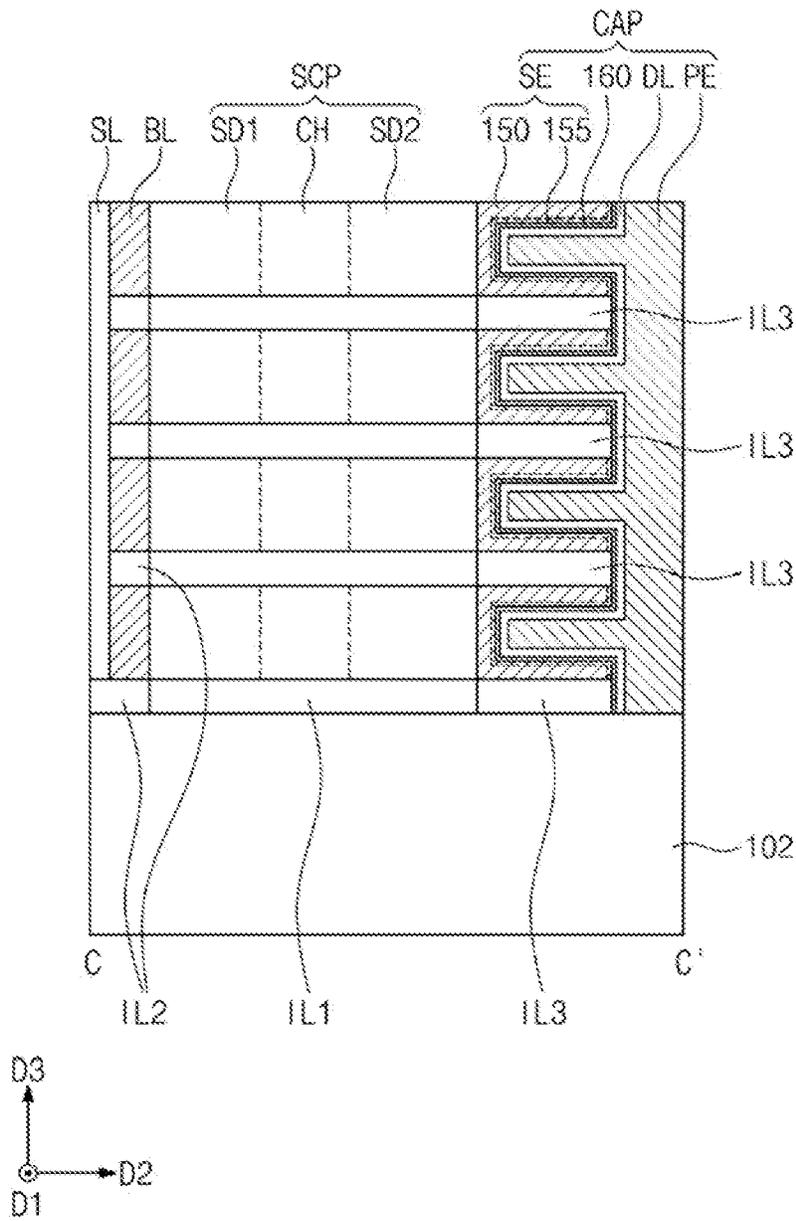


FIG. 17



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# SEMICONDUCTOR DEVICE INCLUDING CAPACITOR WITH PILLAR-SHAPED BOTTOM ELECTRODE

## CROSS-REFERENCE TO RELATED APPLICATIONS

This is a continuation application based on pending application Ser. No. 17/571,935, filed Jan. 10, 2022, the entire contents of which is hereby incorporated by reference.

This U.S. non-provisional patent application claims priority under 35 U.S.C. § 119 to Korean Patent Application No. 10-2021-0088022, filed on Jul. 5, 2021, in the Korean Intellectual Property Office, the entire contents of which are hereby incorporated by reference.

## BACKGROUND

### 1. Field

Embodiments relate to a semiconductor device.

### 2. Description of the Related Art

Due to their small-size, multifunctionality, and/or low-cost characteristics, semiconductor devices are considered important elements in the electronic industry. A memory device, which is one of the semiconductor devices, may store logical data.

## SUMMARY

The embodiments may be realized by providing a semiconductor device including a substrate; bottom electrodes on the substrate, each bottom electrode including a first region and a second region, the second region containing an additional element relative to the first region; a first supporting pattern on the substrate and in contact with a portion of a side surface of each bottom electrode; a top electrode on the bottom electrodes; a dielectric layer between the bottom electrodes and the top electrode; and a capping layer between the bottom electrodes and the dielectric layer, the capping layer covering a top surface and a bottom surface of the first supporting pattern, wherein the second region is in contact with the capping layer, and the capping layer and the dielectric layer include different materials from each other.

The embodiments may be realized by providing a semiconductor device including a substrate; bottom electrodes on the substrate, each of the bottom electrodes including a first region and a second region, the second region being a doped region; a first supporting pattern on the substrate and in contact with a portion of a side surface of each of the bottom electrodes; a top electrode on the bottom electrodes; a dielectric layer between the bottom electrodes and the top electrode; and a capping layer between the bottom electrodes and the dielectric layer, between a top surface of the first supporting pattern and the dielectric layer, and between a bottom surface of the first supporting pattern and the dielectric layer, wherein the second region is between the first region and the capping layer, and the capping layer includes a doping metal.

The embodiments may be realized by providing a semiconductor device including a semiconductor substrate including a device isolation layer, the device isolation layer defining an active region, the active region including a first impurity region and a pair of second impurity regions, which are spaced apart from each other with the first impurity

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region therebetween; a word line in the semiconductor substrate and crossing the active region; a bit line on the semiconductor substrate and crossing the word line, the bit line being connected to the first impurity region; a storage node contact on the semiconductor substrate and connected to the second impurity region; a landing pad electrically connected to the storage node contact; bottom electrodes on the landing pad, each of the bottom electrodes including a first region and a second region, the second region containing an additional element relative to the first region; a top electrode on the bottom electrodes; a supporting pattern between the bottom electrodes; a dielectric layer between the bottom electrodes and the top electrode; and a capping layer between the bottom electrodes and the dielectric layer and covering a top surface and a bottom surface of the supporting pattern, wherein the second region is between the first region and the capping layer.

## BRIEF DESCRIPTION OF THE DRAWINGS

Features will be apparent to those of skill in the art by describing in detail exemplary embodiments with reference to the attached drawings in which:

FIG. 1 is a plan view of a semiconductor device according to an embodiment.

FIG. 2 is a sectional view taken along a line I-I' of FIG. 1.

FIG. 3 is an enlarged sectional view of a portion 'A' of FIG. 2.

FIGS. 4 to 12 are sectional views, which are respectively taken along the line I-I' of FIG. 1 to illustrate stages in a method of fabricating a semiconductor device according to an embodiment.

FIG. 13 is a sectional view of a semiconductor device according to an embodiment.

FIG. 14 is a plan view of a semiconductor device according to an embodiment.

FIG. 15 is a sectional view taken along lines A-A' and B-B' of FIG. 14.

FIG. 16 is a perspective view of a three-dimensional semiconductor memory device according to an embodiment.

FIG. 17 is a sectional view taken along a line C-C' of FIG. 16.

## DETAILED DESCRIPTION

FIG. 1 is a plan view of a semiconductor device according to an embodiment. FIG. 2 is a sectional view taken along a line I-I' of FIG. 1. FIG. 3 is an enlarged sectional view of a portion 'A' of FIG. 2.

Referring to FIGS. 1, 2, and 3, a substrate **100** may be provided. The substrate **100** may be a semiconductor substrate. In an implementation, the substrate **100** may be a silicon substrate, a germanium substrate, or a silicon-germanium substrate.

An interlayer insulating layer **110** may be on the substrate **100**. The interlayer insulating layer **110** may cover at least a portion of a top surface of the substrate **100**. The interlayer insulating layer **110** may be formed of or include an insulating material (e.g., silicon oxide).

A conductive contact **120** may be on the substrate **100**. The conductive contact **120** may penetrate the interlayer insulating layer **110** and may be electrically connected to an interconnection line in the substrate **100**. In an implementation, a plurality of the conductive contacts **120** may be spaced apart from each other horizontally (e.g., in a direction parallel to the top surface of the substrate **100**). The con-

ductive contact **120** may be formed of or include, e.g., doped poly silicon, titanium nitride, or tungsten. As used herein, the term “or” is not an exclusive term, e.g., “A or B” would include A, B, or A and B. In the present specification, the description of two elements being electrically connected/

coupled to each other may mean that the elements are directly connected/coupled to each other or are indirectly connected/coupled to each other through another conductive element.

In an implementation, a device isolation layer may be in the substrate **100** to define active regions. Word lines may be buried in the substrate **100**. The word lines may be electrically disconnected from the substrate **100** by a gate insulating layer and a capping pattern. Impurity injection regions serving as source/drain regions may be in portions of the substrate **100** at both sides of the word lines. Bit lines may be electrically connected to the impurity injection regions, respectively, at sides of the word lines. The conductive contacts **120** may be electrically connected to the impurity injection regions, respectively, which are at other sides of the word lines.

An etch stop layer **130** may be on the interlayer insulating layer **110**. The etch stop layer **130** may cover a top surface of the interlayer insulating layer **110**. The etch stop layer **130** may be formed of or include an insulating material (e.g., silicon oxide, silicon nitride, silicon oxynitride, silicon boron nitride, or silicon carbon nitride). The etch stop layer **130** may be a single layer or a multiple layer.

A bottom electrode BE may be on the substrate **100**. The bottom electrode BE may penetrate the etch stop layer **130** and may be electrically connected to the conductive contact **120**. In an implementation, the bottom electrode BE may have a pillar shape. In an implementation, the bottom electrode BE may have a cylinder shape with a closed bottom surface. In an implementation, a plurality of the bottom electrodes BE may be spaced apart from each other horizontally (e.g., in the direction parallel to the top surface of the substrate **100**). The bottom electrodes BE may be on the conductive contacts **120**, respectively. When viewed in a plan view, the bottom electrodes BE may be arranged to form a honeycomb shape. In an implementation, six bottom electrodes BE may be around one of the bottom electrodes BE to surround the one of the bottom electrodes BE in a hexagonal shape. The bottom electrodes BE may be formed of or include a conductive material (e.g., doped poly silicon, metals, metal oxides, or metal nitrides). In an implementation, the bottom electrodes BE may be formed of or include titanium nitride.

A first supporting pattern **140** and a second supporting pattern **145** may be between the bottom electrodes BE. The first supporting pattern **140** and the second supporting pattern **145** may be vertically spaced apart from each other. The second supporting pattern **145** may be on the first supporting pattern **140**. The first supporting pattern **140** and the second supporting pattern **145** may be in direct contact with side surfaces of the bottom electrodes BE. The first supporting pattern **140** and the second supporting pattern **145** may physically support the bottom electrodes BE. The bottom electrodes BE, which are adjacent to each other, may be connected to each other through the first supporting pattern **140** and the second supporting pattern **145**. The first supporting pattern **140** may connect lower portions of the bottom electrodes BE to each other, and the second supporting pattern **145** may connect upper portions of the bottom electrodes BE to each other. The second supporting pattern **145** may be located at a level higher than the first supporting pattern **140**. In the present specification, the level

may mean a vertical distance measured from the top surface of the substrate **100**. In an implementation, a top surface of the second supporting pattern **145** may be coplanar with a top surface of the bottom electrode BE. In an implementation, the top surface of the second supporting pattern **145** may be located at a level lower than the top surface of the bottom electrode BE. In an implementation, the first supporting pattern **140** and the second supporting pattern **145** may have different thicknesses from each other. The first supporting pattern **140** and the second supporting pattern **145** may be formed of or include, e.g., silicon nitride, silicon boron nitride, or silicon carbon nitride.

Penetration holes TH may be on the substrate **100**. Each of the penetration holes TH may be between three bottom electrodes BE, which are adjacent to each other. Each of the penetration holes TH may expose a portion of a side surface of each of the three bottom electrodes BE, which are adjacent to each other. The penetration holes TH may penetrate the first supporting pattern **140** and the second supporting pattern **145**. Each of the penetration holes TH may expose the etch stop layer **130**.

A capping layer **160** may be on the substrate **100**. The capping layer **160** may conformally cover the bottom electrodes BE, the first supporting pattern **140**, and the second supporting pattern **145**. The capping layer **160** may conformally cover an inner side surface and a bottom surface of each of the penetration holes TH. The capping layer **160** may be in contact with portions of the bottom electrodes BE, which are not covered with the first supporting pattern **140** and the second supporting pattern **145**, and may be in contact with a top surface of the etch stop layer **130**. The capping layer **160** may also be in contact with a top surface and a bottom surface of the first supporting pattern **140** and may be in contact with a top surface and a bottom surface of the second supporting pattern **145**. The capping layer **160** may be in an electrically insulating state. In an implementation, the bottom electrodes BE, which are horizontally spaced apart from each other, may not be electrically connected to each other by or through the capping layer **160**. The capping layer **160** may be formed of or include a different material from the bottom electrodes BE. In an implementation, the capping layer **160** may be formed of or include a metallic material that is different from a metallic material in a first region **150** to be described below. The capping layer **160** may be formed of or include, e.g., a metal oxide or a metal oxynitride. In an implementation, a metallic material in the capping layer **160** may be a doping metal. The doping metal in the capping layer **160** may include a material having a large bandgap. In an implementation, the bandgap of the doping metal in the capping layer **160** may range from 3 eV to 12 eV. The doping metal in the capping layer **160** may include, e.g., Ta, V, Mo, Cr, Sb, Co, Ni, Fe, Nb, or Cu. In an implementation, the capping layer **160** may be formed of or include, e.g., tantalum oxide, vanadium oxide, tantalum oxynitride, or vanadium oxynitride. In an implementation, a thickness T1 of the capping layer **160** may range from 0.05 nm to 0.5 nm.

A dielectric layer DL may be on the substrate **100**. The dielectric layer DL may conformally cover a top surface of the capping layer **160**. The dielectric layer DL may partially fill the penetration holes TH and may be extended to a region on the top surface of the capping layer **160**. In an implementation, the capping layer **160** may be between the bottom electrodes BE and the dielectric layer DL and between the top surface of the etch stop layer **130** and the dielectric layer DL. The capping layer **160** may be between the top surface of the first supporting pattern **140** and the dielectric layer DL

and between the bottom surface of the first supporting pattern **140** and the dielectric layer DL. The capping layer **160** may be between the top surface of the second supporting pattern **145** and the dielectric layer DL and between the bottom surface of the second supporting pattern **145** and the dielectric layer DL. The dielectric layer DL may be spaced apart from the bottom electrode BE, the first supporting pattern **140**, and the second supporting pattern **145** and may not be in contact with the bottom electrode BE, the first supporting pattern **140**, and the second supporting pattern **145**. The dielectric layer DL may be formed of or include a material different from the capping layer **160**. The dielectric layer DL may be formed of or include, e.g., a silicon oxide or a metal oxide. In an implementation, the dielectric layer DL may be formed of or include, e.g., hafnium oxide, aluminum oxide, zirconium oxide, or lanthanum oxide.

Each of the bottom electrodes BE may include the first region **150** and a second region **155**. The first region **150** may be spaced apart from the capping layer **160** and may not be in contact with the capping layer **160**. The first region **150** may be in direct contact with the first supporting pattern **140** and the second supporting pattern **145**. The first region **150** may correspond to most of the bottom electrode BE. The second region **155** may be a region containing an additional element. In an implementation, the additional element may be a doping metal, and the second region **155** may be a doped region. The second region **155** may be between the first region **150** and the capping layer **160**. The second region **155** may be adjacent to or at side and top surfaces of the bottom electrode BE. The second region **155** may be in direct contact with the capping layer **160**. In an implementation, when viewed in a plan view, the second region **155** may have an arc shape, between the first region **150** of the bottom electrode BE and the capping layer **160**.

The first region **150** may be formed of or include a conductive material (e.g., a metal nitride). In an implementation, the first region **150** may be formed of or include, e.g., titanium nitride, tantalum nitride, or tungsten nitride. In an implementation, the second region **155** may include the same doping metal as the doping metal in the capping layer **160**. In an implementation, the second region **155** may include a metal nitride containing a doping metal. The doping metal in the second region **155** may include a material with a large bandgap. The bandgap of the doping metal in the second region **155** may range from 3 eV to 12 eV. The doping metal in the second region **155** may be formed of or include, e.g., Ta, V, Mo, Cr, Sb, Co, Ni, Fe, Nb, or Cu. In an implementation, the second region **155** may include titanium nitride containing the doping metal. In an implementation, the second region **155** may be formed of or include, e.g., tantalum-doped titanium nitride or vanadium-doped titanium nitride. In an implementation, the second region **155** may be formed of or include, e.g., titanium-doped tantalum nitride or titanium-doped vanadium nitride. A concentration of the doping metal in the second region **155** may decrease with decreasing distance to the first region **150**. In an implementation, the doping metal in the capping layer **160** may be the same as one of metallic elements in the second region **155**. In an implementation, the one of the metallic elements in the second region **155** may be the doping metal. In an implementation, a concentration of the doping metal in the capping layer **160** may be higher than a concentration of the doping metal in the second region **155**.

A top electrode TE may be on the dielectric layer DL. The top electrode TE may fill remaining portions of the penetration holes TH. In an implementation, the dielectric layer DL may be between the top electrode TE and the capping layer

**160**. The top electrode TE may be formed of or include, e.g., titanium nitride, doped polysilicon, or doped silicon germanium. The top electrode TE may be a single layer or a multiple layer. The bottom electrodes BE, the dielectric layer DL, and the top electrode TE may constitute a capacitor CAP. In an implementation, the capacitor CAP may serve as a data storing element in a semiconductor device according to an embodiment.

According to an embodiment, the capping layer **160**, which includes a doping metal having a large bandgap, may be between the bottom electrode BE and the dielectric layer DL. In this case, when a voltage is applied to the bottom electrode BE, it is possible to help suppress a depletion region from being formed, to help increase an electrostatic capacitance of a capacitor, and to help reduce an equivalent oxide thickness (EOT). In addition, due to the presence of the capping layer **160**, electrons in the bottom electrode BE may be hardly leaked, and thus, it is possible to help reduce a leakage current in the semiconductor device. Furthermore, the capping layer **160** may be in an electrically insulating state, a bridge defect issue in the semiconductor device may be reduced, and thus, the semiconductor device may have an improved reliability property.

FIGS. **4** to **12** are sectional views, which are respectively taken along the line I-I' of FIG. **1** to illustrate stages in a method of fabricating a semiconductor device according to an embodiment. For concise description, a previously described element may be identified by the same reference number without repeating an overlapping description thereof.

Referring to FIG. **4**, the substrate **100** may be provided. The interlayer insulating layer **110** may be formed on the substrate **100**. The conductive contacts **120** may be formed in the interlayer insulating layer **110**. The etch stop layer **130** may be formed on the substrate **100**. The etch stop layer **130** may be formed to cover a top surface of the interlayer insulating layer **110** and top surfaces of the conductive contacts **120**. A first mold layer **112**, a first supporting layer **142**, a second mold layer **115**, and a second supporting layer **147** may be sequentially formed on the etch stop layer **130**. The first supporting layer **142** may be formed of or include a material having an etch selectivity with respect to the first mold layer **112**. The second mold layer **115** may be formed of or include a material having an etch selectivity with respect to the first supporting layer **142**. The first mold layer **112** and the second mold layer **115** may be formed of or include the same material. In an implementation, the first mold layer **112** and the second mold layer **115** may be formed of or include silicon oxide. The first supporting layer **142** and the second supporting layer **147** may be formed of or include the same material. In an implementation, the first supporting layer **142** and the second supporting layer **147** may be formed of or include, e.g., silicon nitride, silicon boron nitride, or silicon carbon nitride.

Referring to FIG. **5**, the second supporting layer **147**, the second mold layer **115**, the first supporting layer **142**, the first mold layer **112**, and the etch stop layer **130** may be sequentially etched to form contact holes **150H** exposing the conductive contacts **120**, respectively. In an implementation, the etching process may include an anisotropic etching process (e.g., a dry etching process).

Referring to FIG. **6**, the bottom electrodes BE may be formed in the contact holes **150H**, respectively. The formation of the bottom electrodes BE may include forming a conductive layer on the substrate **100** to fill the contact holes **150H** and performing a planarization process on the conductive layer. In an implementation, the bottom electrodes

BE may be formed by, e.g., chemical vapor deposition (CVD), atomic layer deposition (ALD), or physical vapor deposition (PVD) processes. In an implementation, the planarization process may include an etch-back or chemical mechanical polishing (CMP) process. A top surface of the second supporting layer **147** may be exposed by the planarization process.

Referring to FIG. 7, a mask pattern **190** may be formed on the second supporting layer **147** and the bottom electrodes BE. The mask pattern **190** may have openings **190H**, which are formed to partially expose top surfaces of some of the bottom electrodes BE. In an implementation, each of the openings **190H** may be formed to partially expose the top surfaces of three adjacent ones of the bottom electrodes BE and the top surface of the second supporting layer **147** therebetween.

Referring to FIG. 8, an etching process using the mask pattern **190** as an etch mask may be performed on the second supporting layer **147** exposed through the openings **190H**, the second mold layer **115** thereunder, and the first supporting layer **142** thereunder. As a result of the etching process, support holes **145H** may be formed to expose portions of the top surface of the first mold layer **112** and portions of the top surface of the bottom electrode BE. As a result of the etching process, the second supporting layer **147** may be patterned to form the second supporting pattern **145**, and the first supporting layer **142** may be patterned to form the first supporting pattern **140**. The etching process may include, e.g., an anisotropic etching process.

Referring to FIG. 9, the mask pattern **190** may be removed. In an implementation, the mask pattern **190** may be removed by performing ashing and strip processes. An etching process may be performed to remove the second mold layer **115** and the first mold layer **112** exposed through the support holes **145H**. As a result of the etching process, the penetration holes TH may be formed to expose the top surface of the etch stop layer **130**, the side surfaces of the bottom electrodes BE, the bottom surface of the second supporting pattern **145**, and the top and bottom surfaces of the first supporting pattern **140**. In an implementation, the etching process may include an isotropic etching process.

In an implementation, the second supporting pattern **145** may be formed by etching the second supporting layer **147** through an anisotropic etching process, and the second mold layer **115**, which is exposed through the anisotropic etching process, may be removed by an isotropic etching process. In an implementation, the second mold layer **115** may be removed by a wet etching process using an etching solution having an etch selectivity with respect to the first and second supporting layers **142** and **147**. Thereafter, the first supporting pattern **140** may be formed by etching the first supporting layer **142** through an anisotropic etching process, and then, the first mold layer **112**, which is exposed through the anisotropic etching process, may be removed. In an implementation, the first mold layer **112** may be removed by a wet etching process using an etching solution having an etch selectivity with respect to the etch stop layer **130** and the first supporting layer **142**. Accordingly, the penetration holes TH may be formed to expose the top surface of the etch stop layer **130**.

Referring to FIG. 10, a preliminary capping layer **165** may be formed on the substrate **100**. The preliminary capping layer **165** may conformally cover the bottom electrodes BE, the first supporting pattern **140**, and the second supporting pattern **145**. The preliminary capping layer **165** may conformally cover an inner side surface and a bottom surface of each of the penetration holes TH. In an imple-

mentation, the preliminary capping layer **165** may conformally cover the side surfaces of the bottom electrodes BE, the top and bottom surfaces of the first supporting pattern **140**, the top and bottom surfaces of the second supporting pattern **145**, and the top surface of the etch stop layer **130**. The preliminary capping layer **165** may be formed by a layer-forming technique having a good step coverage property (e.g., by an atomic layer deposition (ALD) or chemical vapor deposition (CVD) process). The preliminary capping layer **165** may be formed of or include, e.g., a metal (e.g., non-compounded metal), a metal oxide, or a metal nitride. The metal in the preliminary capping layer **165** may be a doping metal. The doping metal may include a material having a large bandgap. In an implementation, the bandgap of the doping metal may range from 3 eV to 12 eV. The doping metal in the preliminary capping layer **165** may include, e.g., Ta, V, Mo, Cr, Sb, Co, Ni, Fe, Nb, or Cu. In an implementation, the preliminary capping layer **165** may be formed of or include, e.g., tantalum, vanadium, tantalum oxide, vanadium oxide, tantalum nitride, or vanadium nitride.

Referring to FIG. 11, the second regions **155** may be formed by performing a thermal treatment process on the substrate **100**. As a result of the thermal treatment process, the doping metal in the preliminary capping layer **165** may be diffused into each of the bottom electrodes BE to form the second region **155** and the first region **150**. Accordingly, each of the bottom electrodes BE may include the first region **150**, into which the doping metal has not been diffused, and the second region **155**, into which the doping metal has been diffused. In an implementation, the second region **155** may include the same doping metal as the doping metal in the preliminary capping layer **165**. In an implementation, the second region **155** may be formed of or include titanium nitride containing the doping metal. In an implementation, the second region **155** may be formed of or include tantalum-doped titanium nitride or vanadium-doped titanium nitride. In the case where a concentration of the doping metal in the preliminary capping layer **165** is high, the second region **155** may have a structure, in which a metallic element of the bottom electrode BE is diffused as a doping metal, and the doping metal in the preliminary capping layer **165** may be formed in the form of metal nitride. In an implementation, the second region **155** may be formed of or include titanium-doped tantalum nitride or titanium-doped vanadium nitride. The doping metal may be diffused into the second region **155** from the preliminary capping layer **165**, and a concentration of the doping metal in the second region **155** may decrease with decreasing distance to the first region **150** (e.g., with increasing distance from the preliminary capping layer **165**). The doping metal in the preliminary capping layer **165** may be the same as one of metallic elements in the second region **155**. In an implementation, the one of the metallic elements in the second region **155** may be the doping metal. In an implementation, a concentration of the doping metal in the preliminary capping layer **165** may be higher than a concentration of the doping metal in the second region **155**. The thermal treatment process may be performed at temperature of 100° C. to 500° C.

By contrast, during the thermal treatment process, the doping metal in the preliminary capping layer **165** may not be diffused into the first supporting pattern **140** and the second supporting pattern **145**. In an implementation, the doping metal in the preliminary capping layer **165** may include a material having a large bandgap, and the doping

metal in the preliminary capping layer **165** may be selectively diffused into only the bottom electrodes **BE**.

Referring to FIG. **12**, the dielectric layer **DL** may be formed on the preliminary capping layer **165**. The dielectric layer **DL** may conformally cover the preliminary capping layer **165**. The dielectric layer **DL** may fill a portion of each of the penetration holes **TH** and may be extended to a region on a top surface of the preliminary capping layer **165**. The dielectric layer **DL** may be formed by a layer-forming technique having a good step coverage property (e.g., by an atomic layer deposition (ALD) or chemical vapor deposition (CVD) process). The preliminary capping layer **165** may be oxidized by the dielectric layer **DL** to form the capping layer **160**. The capping layer **160** may be in an electrically insulating state. In an implementation, the bottom electrodes **BE**, which are horizontally spaced apart from each other, may not be electrically connected to each other by or through the capping layer **160**. The capping layer **160** may be formed of or include, e.g., a metal oxide or a metal oxynitride. A metallic element in the capping layer **160** may be the same as the doping metal in the preliminary capping layer **165**. The capping layer **160** may be formed of or include, e.g., tantalum oxide, vanadium oxide, tantalum oxynitride, or vanadium oxynitride.

Referring back to FIGS. **1** and **2**, the top electrode **TE** may be formed on the dielectric layer **DL**. The top electrode **TE** may cover the dielectric layer **DL**. The top electrode **TE** may fill a space between the bottom electrodes **BE** and a remaining portion of the penetration hole **TH**.

In other methods, a process of removing a preliminary capping layer may be performed before the formation of a dielectric layer. The second region may also be etched during the removal process, and this could lead to a technical problem, such as a reduction in an amount of dopants in a bottom electrode.

By contrast, according to an embodiment, a process of removing the preliminary capping layer **165** may not be performed before the formation of the dielectric layer **DL**. The dielectric layer **DL** may be formed on the preliminary capping layer **165** without removal of the preliminary capping layer **165**, and an amount of dopants in the bottom electrode **BE** may be maximized. Furthermore, the additional removal process may not be performed, and it is possible to simplify the fabrication process and to reduce fabrication cost.

Furthermore, according to an embodiment, the preliminary capping layer **165** may include a doping metal having a large bandgap, and the doping metal may be selectively diffused only into the bottom electrode **BE**.

FIG. **13** is a sectional view of a semiconductor device according to an embodiment. For concise description, a previously described element may be identified by the same reference number without repeating an overlapping description thereof.

Referring to FIG. **13**, a semiconductor device according to an embodiment may include the substrate **100**, the interlayer insulating layer **110**, the conductive contact **120**, the etch stop layer **130**, the bottom electrodes **BE**, the first supporting pattern **140**, the second supporting pattern **145**, the capping layer **160**, the dielectric layer **DL**, and the top electrode **TE**. Each of the bottom electrodes **BE** may include the first region **150** and the second region **155**. In an implementation, the bottom electrode **BE** may be shaped like a hollow cup or cylinder. The second region **155** may be adjacent to or at an outer side surface **150S1**, an inner side surface **150S2**, a bottom surface, and a top surface of the bottom electrode **BE**. The outer side surface **150S1** of the bottom electrode **BE**

may correspond to the penetration hole **TH**. The capping layer **160** may conformally cover the bottom electrodes **BE**, the first supporting pattern **140**, and the second supporting pattern **145**. In an implementation, the capping layer **160** may conformally cover inner side surfaces and bottom surfaces of the penetration holes **TH** and may conformally cover the outer side surface **150S1**, the inner side surface **150S2**, and the bottom surface of the bottom electrode **BE**. Except for the afore-described features, the semiconductor device according to the present embodiment may be substantially the same as that described with reference to FIGS. **1** and **2**.

FIG. **14** is a plan view of a semiconductor device according to an embodiment. FIG. **15** is a sectional view taken along lines A-A' and B-B' of FIG. **14**.

Referring to FIGS. **14** and **15**, a semiconductor substrate **301** may be provided. The semiconductor substrate **301** may be, e.g., a silicon substrate, a germanium substrate, or a silicon-germanium substrate. A device isolation layer **302** may be in the semiconductor substrate **301**. The device isolation layer **302** may be formed of or include an insulating material (e.g., silicon oxide). The device isolation layer **302** may define active regions **ACT** of the semiconductor substrate **301**. When viewed in a plan view, each of the active regions **ACT** may have a bar-shaped pattern extending in a first direction **D1**. When viewed in a plan view, the active regions **ACT** may correspond to portions of the semiconductor substrate **301** surrounded by the device isolation layer **302**.

Word lines **WL** may cross the active regions **ACT**. The word lines **WL** may be in grooves, which are formed in the device isolation layer **302** and the active regions **ACT**. The word lines **WL** may be parallel to a second direction **D2** crossing the first direction **D1**. The word lines **WL** may be formed of or include a conductive material. A gate dielectric layer **307** may be between each of the word lines **WL** and an inner surface of each of the grooves. In an implementation, the bottoms of the grooves may be located at a relatively deep level in the device isolation layer **302** and may be located at a relatively shallow level in the active regions **ACT**. The gate dielectric layer **307** may be formed of or include, e.g., silicon oxide, silicon nitride, silicon oxynitride, or high-k dielectric materials. The word line **WL** may have a curved bottom surface.

A first impurity region **312a** may be in each of the active regions **ACT** between a pair of the word lines **WL**, and a pair of second impurity regions **312b** may be respectively disposed in opposite edge regions of each of the active regions **ACT**. In an implementation, the pair of the second impurity regions **312b** may be spaced apart from each other with the first impurity region **312a** interposed therebetween. In an implementation, the first and second impurity regions **312a** and **312b** may be doped with n-type impurities. The first impurity region **312a** may correspond to a common drain region, and the second impurity regions **312b** may correspond to a source region. Each of the word lines **WL** and the first and second impurity regions **312a** and **312b** adjacent thereto may constitute a transistor. The word line **WL** may be in the groove, and a channel length of a channel region below the word line **WL** may be increased within a given planar area.

Top surfaces of the word lines **WL** may be lower than top surfaces of the active regions **ACT**. A word line capping pattern **310** may be on each of the word lines **WL**. Each of the word line capping patterns **310** may be a line-shaped pattern, which is extended in a length direction of the word lines **WL** and covers the entire top surface of a correspond-

ing one of the word lines WL. The word line capping patterns **310** may fill the grooves on the word lines WL. The word line capping pattern **310** may be formed of or include, e.g., silicon nitride.

An interlayer insulating pattern **305** may be on the semiconductor substrate **301**. The interlayer insulating pattern **305** may be formed of or include insulating materials and may have a single- or multi-layered structure. The interlayer insulating pattern **305** may be formed of or include, e.g., silicon oxide, silicon nitride, or silicon oxynitride. When viewed in a plan view, the interlayer insulating pattern **305** may be an isolated island-shaped pattern. The interlayer insulating pattern **305** may be formed to cover both of end portions of a pair of the active regions ACT, which are adjacent to each other.

The semiconductor substrate **301**, the device isolation layer **302**, and an upper portion of the word line capping pattern **310** may be partially recessed to form a first recess region R1. When viewed in a plan view, the first recess region R1 may have a mesh shape. A side surface of the first recess region R1 may be aligned to a side surface of the interlayer insulating pattern **305**.

Bit lines BL may be on the interlayer insulating pattern **305**. The bit lines BL may be electrically connected to the first impurity region **312a**. The bit lines BL may cross the word line capping patterns **310** and the word lines WL. The bit lines BL may be parallel to a third direction D3 crossing the first and second directions D1 and D2. The bit lines BL may include a first bit line pattern **330**, a second bit line pattern **331**, and a third bit line pattern **332**, which are sequentially stacked. The first bit line pattern **330** may be formed of or include, e.g., doped or undoped polysilicon. The second bit line pattern **331** may be formed of or include a metal silicide. The third bit line pattern **332** may be formed of or include, e.g., a metallic material (e.g., tungsten, titanium, and tantalum) or a conductive metal nitride (e.g., titanium nitride, tantalum nitride, and tungsten nitride). A bit line capping pattern **337** may be on each of the bit lines BL. The bit line capping patterns **337** may be formed of or include an insulating material (e.g., silicon nitride).

Bit line contacts DC may be in the first recess regions R1 crossing the bit lines BL. The bit line contacts DC may be formed of or include, e.g., doped or undoped polysilicon. A side surface of the bit line contact DC may be in contact with a side surface of the interlayer insulating pattern **305**. A side surface of the bit line contact DC in contact with the interlayer insulating pattern **305** may be concave. The bit line contact DC may electrically connect the first impurity region **312a** to the bit line BL.

A lower gapfill insulating pattern **341** may be in a portion of the first recess region R1 which is not occupied by the bit line contact DC. The lower gapfill insulating pattern **341** may be formed of or include an insulating material and may have a single- or multi-layered structure. The lower gapfill insulating pattern **341** may be formed of or include, e.g., silicon oxide, silicon nitride, or silicon oxynitride.

Storage node contacts BC may be between an adjacent pair of the bit lines BL. The storage node contacts BC may be spaced apart from each other. The storage node contacts BC may be electrically connected to the second impurity regions **312b**. In an implementation, the storage node contacts BC may be formed of or include doped or undoped polysilicon. Top surfaces of the storage node contacts BC may be concave.

A spacer SP may be between the bit line BL and the storage node contact BC. The spacer SP may include a first spacer **321** and a second spacer **325**, which are spaced apart

from each other by a gap region GP. In the present specification, the gap region GP may be referred to as an air gap region. The first spacer **321** may cover a side surface of the bit line BL and a side surface of the bit line capping pattern **337**. The second spacer **325** may be adjacent to the storage node contact BC. The first spacer **321** and the second spacer **325** may be formed of or include the same material. The first spacer **321** and the second spacer **325** may be formed of or include, e.g., silicon nitride.

A bottom surface of the second spacer **325** may be lower than a bottom surface of the first spacer **321**. A top surface of the second spacer **325** may be lower than a top surface of the first spacer **321**. In this case, it is possible to help increase a process margin in a subsequent process of forming a landing pad LP and to help improve reliability in connection between the landing pad LP and the storage node contact BC. In an implementation, the first spacer **321** may be extended to cover the side surface of the bit line contact DC and the side and bottom surfaces of the first recess region R1. In an implementation, the first spacer **321** may be between the bit line contact DC and the lower gapfill insulating pattern **341**, between the word line capping pattern **310** and the lower gapfill insulating pattern **341**, between the semiconductor substrate **301** and the lower gapfill insulating pattern **341**, and between the device isolation layer **302** and the lower gapfill insulating pattern **341**.

A storage node ohmic layer **309** may be on the storage node contact BC. The storage node ohmic layer **309** may be formed of or include, e.g., a metal silicide. A diffusion prevention pattern **311a** may conformally cover the storage node ohmic layer **309**, the first and second spacers **321** and **325**, and the bit line capping patterns **337**. The diffusion prevention pattern **311a** may be formed of or include a metal nitride (e.g., titanium nitride and tantalum nitride). The landing pad LP may be on the diffusion prevention pattern **311a**. The landing pad LP may be electrically connected to the storage node contact BC. The landing pads LP may correspond to the conductive contact **120** of FIG. 2. The landing pad LP may be formed of or include a metal material (e.g., tungsten). A top surface of the landing pad LP may have a width larger than the storage node contact BC. A center of the landing pad LP may be shifted from a center of the storage node contact BC in the second direction D2. A portion of the bit line BL may be vertically overlapped with the landing pad LP. An upper side surface of the bit line capping pattern **337** may be overlapped with the landing pad LP and may be covered with a third spacer **327**. A pad separation pattern **357** may be between the landing pads LP. The pad separation pattern **357** may correspond to the interlayer insulating layer **110** of FIG. 2. The pad separation pattern **357** may be formed of or include, e.g., silicon nitride, silicon oxide, silicon oxynitride, or a porosity material.

The etch stop layer **130** may be on the pad separation pattern **357**. The etch stop layer **130** may cover a top surface of the pad separation pattern **357**. The bottom electrodes BE may be on the landing pads LP, respectively. Each of the bottom electrodes BE may include the first region **150** and the second region **155**. The first supporting pattern **140** may be between the bottom electrodes BE. Portions of the side surfaces of the bottom electrodes BE may be connected to the first supporting pattern **140**. The capping layer **160** may be on the semiconductor substrate **301**. The capping layer **160** may conformally cover the bottom electrodes BE and the first supporting pattern **140**. The dielectric layer DL may be on the substrate **100**. The dielectric layer DL may conformally cover the top surface of the capping layer **160**. The top electrode TE may be on the dielectric layer DL. The

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etch stop layer **130**, the bottom electrodes BE, the first region **150**, the second region **155**, the first supporting pattern **140**, the capping layer **160**, the dielectric layer DL, and the top electrode TE may be configured to have the same features as those described with reference to FIGS. **1** to **3**.

According to an embodiment, it is possible to help reduce a parasitic capacitance between the bit line BL and the storage node contact BC, because the gap region GP may be between the first and second spacers **321** and **325** and permittivity of the air or vacuum is smaller than that of silicon oxide.

FIG. **16** is a perspective view of a three-dimensional semiconductor memory device according to an embodiment. FIG. **17** is a sectional view taken along a line C-C' of FIG. **16**. For concise description, a previously described element may be identified by the same reference number without repeating an overlapping description thereof.

Referring to FIGS. **16** and **17**, semiconductor patterns SCP may be on a lower substrate **102**. The semiconductor patterns SCP may be spaced apart from each other in two different directions (e.g., the first and third directions D1 and D3). Each of the semiconductor patterns SCP may be a bar-shaped pattern that is elongated in the second direction D2 crossing the first and third directions D1 and D3. The first and second directions D1 and D2 may be parallel to a top surface of the lower substrate **102**. The third direction D3 may be perpendicular to the top surface of the lower substrate **102**. Each of the semiconductor patterns SCP may have a first end portion E1 and a second end portion E2, which are spaced apart from each other. Each of the semiconductor patterns SCP may have a first side surface SW1 and a second side surface SW2, which connect the first end portion E1 to the second end portion E2 and are spaced apart from each other. The semiconductor patterns SCP may be formed of or include, e.g., silicon or germanium. Each of the semiconductor patterns SCP may include a first source/drain region SD1 adjacent to the first end portion E1, a second source/drain region SD2 adjacent to the second end portion E2, and a channel region CH between the first and second source/drain regions SD1 and SD2. Each of the first and second source/drain regions SD1 and SD2 may be an impurity or doped region, which is formed in the semiconductor pattern SCP. In an implementation, the channel region CH may also be doped with impurities. In an implementation, the first and second source/drain regions SD1 and SD2 may be doped to have a first conductivity type, and the channel region CH may be doped to have a second conductivity type different from the first conductivity type.

The bit lines BL may be stacked on the lower substrate **102** and may be spaced apart from each other in the third direction D3. The bit lines BL may be extended in the first direction D1. The first end portions E1 of the semiconductor patterns SCP, which are located at the same level, may be connected in common to a corresponding one of the bit lines BL.

A first electrode SE may be connected to the second end portions E2 of the semiconductor patterns SCP. The first electrode SE may correspond to the bottom electrode BE of FIGS. **1** and **2**. The first electrode SE may include the first region **150** and the second region **155**. The first region **150** and the second region **155** may have the same features as those described with reference to FIGS. **1** to **3**. The first electrode SE may be shaped like a 90 degree rotated hollow cup or cylinder.

First word lines WL1 may be adjacent to the first side surfaces SW1 of the semiconductor patterns SCP. Second word lines WL2 may be adjacent to the second side surfaces

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SW2 of the semiconductor patterns SCP. The first and second word lines WL1 and WL2 may be extended from the top surface of the lower substrate **102** in the third direction D3. Each of the first word lines WL1 may be spaced apart from a corresponding one of the second word lines WL2 with the channel regions CH of the semiconductor patterns SCP therebetween. A gate insulating layer Gox may be between the first and second word lines WL1 and WL2 and the semiconductor patterns SCP. The gate insulating layer Gox may be formed of or include, e.g., a high-k dielectric material, silicon oxide, silicon nitride, or silicon oxynitride. In an implementation, the high-k dielectric material may include hafnium oxide, hafnium silicon oxide, lanthanum oxide, zirconium oxide, zirconium silicon oxide, tantalum oxide, titanium oxide, barium strontium titanium oxide, barium titanium oxide, strontium titanium oxide, lithium oxide, aluminum oxide, lead scandium tantalum oxide, or lead zinc niobate.

Each of the bit lines BL and the first and second word lines WL1 and WL2 may be formed of or include a conductive material. The conductive material may include, e.g., a doped semiconductor material (e.g., doped silicon, doped germanium, or the like), a conductive metal nitride (e.g., titanium nitride, tantalum nitride, or the like), a metallic material (e.g., tungsten, titanium, tantalum, or the like), or a metal-semiconductor compound (e.g., tungsten silicide, cobalt silicide, titanium silicide, or the like).

The bit lines BL may be extended in the first direction D1. The bit lines BL may be in contact with an insulating isolation pattern SL. When viewed in a plan view, the insulating isolation pattern SL may have a line shape extending in the first direction D1.

The first word lines WL1 may serve as gate electrodes actually controlling charge conduction through the channel regions CH. The second word lines WL2 may serve as back gate electrodes, which control the movement of electric charges in the channel regions CH. A first interlayer insulating layer IL1 may be between the semiconductor patterns SCP. A second interlayer insulating layer IL2 may be between the bit lines BL. A third interlayer insulating layer IL3 may be between the first electrodes SE. The third interlayer insulating layer IL3 may support the first electrodes SE. The insulating isolation pattern SL may be in contact with side surfaces of the bit lines BL and the second interlayer insulating layers IL2. Each of the first to third interlayer insulating layers IL1, IL2, and IL3 and the insulating isolation pattern SL may be formed of or include, e.g., silicon oxide, silicon oxynitride, or silicon nitride.

The first electrode SE may be in contact with the third interlayer insulating layer IL3. The capping layer **160** may be on the first electrode SE to cover the first electrode SE. The dielectric layer DL may be on the capping layer **160** to cover the capping layer **160**. The capping layer **160** may be between the first electrode SE and the dielectric layer DL. A second electrode PE may be on the dielectric layer DL. The dielectric layer DL may be in contact with the second electrode PE. The second electrode PE may correspond to the top electrode TE of FIGS. **1** and **2**. The first electrode SE, the dielectric layer DL, and the second electrode PE may constitute the capacitor CAP. The capping layer **160** and the dielectric layer DL may have substantially the same features as those described with reference to FIGS. **1** to **3**.

By way of summation and review, with the development of the electronics industry, the memory device is becoming more highly integrated. As a result, linewidths of elements constituting the memory device may be decreasing.

A memory device may have higher reliability, in addition to the higher integration density. An increase in integration density of the memory device could cause deterioration in reliability of the memory device.

According to an embodiment, a capping layer, which includes a doping metal having a large bandgap, may be between a bottom electrode and a dielectric layer. In this case, when a voltage is applied to the bottom electrode BE, it is possible to help suppress formation of a depletion region, to help increase an electrostatic capacitance of a capacitor, and to help reduce an equivalent oxide thickness (EOT). In addition, due to the presence of the capping layer, electrons in the bottom electrode may be hardly leaked, and thus, it is possible to help reduce a leakage current in the semiconductor device. Furthermore, the capping layer may be in an electrically insulating state, a bridge defect issue in the semiconductor device may be reduced, and thus, the semiconductor device may have an improved reliability property.

According to an embodiment, a process of removing a preliminary capping layer may not be performed before the formation of the dielectric layer. The dielectric layer may be formed on the preliminary capping layer without removal of the preliminary capping layer, and an amount of dopants in the bottom electrode may be maximized. Furthermore, the additional removal process may not be performed, and it is possible to simplify the fabrication process and to reduce fabrication cost.

One or more embodiments may provide a semiconductor device including a capacitor.

One or more embodiments may provide a semiconductor device including a capacitor with improved reliability.

Example embodiments have been disclosed herein, and although specific terms are employed, they are used and are to be interpreted in a generic and descriptive sense only and not for purpose of limitation. In some instances, as would be apparent to one of ordinary skill in the art as of the filing of the present application, features, characteristics, and/or elements described in connection with a particular embodiment may be used singly or in combination with features, characteristics, and/or elements described in connection with other embodiments unless otherwise specifically indicated. Accordingly, it will be understood by those of skill in the art that various changes in form and details may be made without departing from the spirit and scope of the present invention as set forth in the following claims.

What is claimed is:

1. A semiconductor device, comprising:

a substrate;

a pillar-shaped bottom electrode on the substrate, the pillar-shaped bottom electrode including titanium nitride (TiN) and having a top surface, a first side surface, and a second side surface that is between the first side surface and the substrate;

a first supporting pattern arranged on the substrate and in contact with the first side surface of the pillar-shaped bottom electrode;

a top electrode on the pillar-shaped bottom electrode; a dielectric layer arranged between the pillar-shaped bottom electrode and the top electrode, and including hafnium; and

a capping layer between the pillar-shaped bottom electrode and the dielectric layer,

wherein:

the capping layer includes niobium oxynitride (NbON), the capping layer covers the top surface and the second side surface of the pillar-shaped bottom electrode,

the capping layer covers a top surface and a bottom surface of the first supporting pattern, and the pillar-shaped bottom electrode includes Nb diffused from the capping layer in a region of the pillar-shaped bottom electrode adjacent to the capping layer.

2. The semiconductor device as claimed in claim 1, wherein the dielectric layer includes aluminum or zirconium.

3. The semiconductor device as claimed in claim 1, wherein the capping layer is in contact with the top surface and the bottom surface of the first supporting pattern.

4. The semiconductor device as claimed in claim 1, wherein the capping layer is spaced apart from the first side surface of the pillar-shaped bottom electrode.

5. The semiconductor device as claimed in claim 1, wherein the dielectric layer is spaced apart from the first supporting pattern.

6. The semiconductor device as claimed 1, further comprising a second supporting pattern between the substrate and the first supporting pattern, wherein the capping layer covers a top surface and a bottom surface of the second supporting pattern.

7. The semiconductor device as claimed in claim 6, wherein the dielectric layer is spaced apart from the second supporting pattern.

8. The semiconductor device as claimed in claim 6, wherein a thickness of the first supporting pattern is greater than a thickness of the second supporting pattern.

9. The semiconductor device as claimed in claim 1, wherein the top surface of the pillar-shaped bottom electrode is substantially coplanar with the top surface of the first supporting pattern.

10. The semiconductor device as claimed in claim 1, wherein the top surface of the pillar-shaped bottom electrode is higher than the top surface of the first supporting pattern.

11. A semiconductor device, comprising:

a substrate;

a pillar-shaped bottom electrode on the substrate, the pillar-shaped bottom electrode including titanium nitride (TiN) and having a top surface, a first side surface, and a second side surface that is between the first side surface and the substrate;

a first supporting pattern arranged on the substrate and in contact with the first side surface of the pillar-shaped bottom electrode;

a top electrode on the pillar-shaped bottom electrode;

a dielectric layer arranged between the pillar-shaped bottom electrode and the top electrode, and including hafnium; and

a capping layer between the pillar-shaped bottom electrode and the dielectric layer,

wherein:

the capping layer includes niobium oxide (NbO),

the capping layer covers the top surface and the second side surface of the pillar-shaped bottom electrode,

the capping layer covers a top surface and a bottom surface of the first supporting pattern, and

the pillar-shaped bottom electrode includes Nb diffused from the capping layer in a region of the pillar-shaped bottom electrode adjacent to the capping layer.

12. The semiconductor device as claimed in claim 11, wherein the dielectric layer includes aluminum or zirconium.

13. The semiconductor device as claimed in claim 11, wherein the capping layer is in contact with the top surface and the bottom surface of the first supporting pattern.

14. The semiconductor device as claimed in claim 11, wherein the capping layer is spaced apart from the first side surface of the pillar-shaped bottom electrode.

15. The semiconductor device as claimed in claim 11, wherein the dielectric layer is spaced apart from the first 5 supporting pattern.

16. The semiconductor device as claimed 11, further comprising a second supporting pattern between the substrate and the first supporting pattern, wherein the capping layer covers a top surface and a bottom surface of the second 10 supporting pattern.

17. The semiconductor device as claimed in claim 16, wherein the dielectric layer is spaced apart from the second supporting pattern.

18. The semiconductor device as claimed in claim 16, 15 wherein a thickness of the first supporting pattern is greater than a thickness of the second supporting pattern.

19. The semiconductor device as claimed in claim 11, wherein the top surface of the pillar-shaped bottom electrode is substantially coplanar with the top surface of the first 20 supporting pattern.

20. The semiconductor device as claimed in claim 11, wherein the top surface of the pillar-shaped bottom electrode is higher than the top surface of the first supporting pattern.

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